

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped Silicon	Silicon (Si)	7440-21-3	0.67588	100.0	40.74
			Subtotal	0.67588	100	40.74
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.53088	100.0	32
			Subtotal	0.53088	100	32
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01986	0.03	1.197
	Copper alloy	Iron (Fe)	7439-89-6	0.06619	0.1	3.99
	Copper alloy	Copper (Cu)	7440-50-8	66.10791	99.87	3,984.813
			Subtotal	66.19396	100	NaN
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.06288	6.5	124.345
	Polymer	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	5.07786	16.0	306.08
	Filler	Silica fused	60676-86-0	22.53299	71.0	1,358.23
	Flame retardant	Metal hydroxide		2.06288	6.5	124.345
			Subtotal	31.73661	100	NaN
Post-plating	Lead alloy	Tin (Sn)	7440-31-5	0.36498	100.0	22
			Subtotal	0.36498	100	22
Solder Wire	Lead alloy	Tin (Sn)	7440-31-5	0.02488	5.0	1.5
	Lead alloy	Silver (Ag)	7440-22-4	0.01244	2.5	0.75
	Lead alloy	Lead (Pb)	7439-92-1	0.46037	92.5	27.75
			Subtotal	0.49769	100	30
			Total	100	100	NaN

Disclaimer

All information in this document is furnished for exploratory or indicative purposes only. All information in this document is believed to be accurate and reliable. However, WeEn Semiconductors does not give any representations or warranties as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. WeEn Semiconductors may make changes to information published in this document at any time and without notice. Minor deviations may occur in the products from different manufacturing location. This document supersedes and replaces all information supplied prior to the publication hereof. Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.